

HM33-10040LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (mg)	Composition (mg)
1	CORE	Toroid Core	Iron(III) Oxide (Fe ₂ O ₃)	1309-37-1	120	84
			Manganese(II) Oxide (MnO)	1344-43-0		24
			Zinc Oxide (ZnO)	1314-13-2		12
2	BODY	Bobbin	Phenolic Resin	9003-35-4	50	23.75
			Phenolic Resin	108-95-2		0.75
			Wood Flour	-		12.5
			Magnesium Hydrate	1309-42-5		5
			Zinc Borate	138265-88-0		4
			Stearic Acid	61790-38-3		2
			Carbon Black	1333-86-1		20
3	WIRE	UEW	Copper(Cu)	7440-50-8	30	29.4
			Polyurethane (PU)	-		0.6
4	TAPE	Polyster	Silicomne Polymer	-	10	7
			PolyImide Film	-		3
5	PIN	Lead	Fe(Iron)	7439-89-6	30	8.4
			Cu(Copper)	7440-50-8		21
			Sn(Tin)	7440-31-5		0.6
6	BODY	Clip	Copper(Cu)	7440-50-8	116.2	107.69997
			Sn(Tin)	7440-31-5		8.134
			Ni	7440-02-0		0.36603
7	ADHESIVE	Epoxy 3300LD-1 A Black	Epoxy Resin	24969-06-0	50	45
			Silica Fused (SiO ₂)	60676-86-0		5
		Epoxy 3300LD-1 B Limpid	C ₁₃ H ₁₄ N ₂	101-77-9	50	48
			Silica Fused (SiO ₂)	60676-86-0		2
8	SOLDER	Lead Free Solder	Tin (Sn)	7440-31-5	20	19.3
			Silver (Ag)	7440-21-3		0.6
			Copper (Cu)	7440-50-8		0.1

Total Weight	476.2
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